

SOT569-2

plastic thin fine-pitch ball grid array package; 144 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA144
Package type industry code	TFBGA144
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	14-3-2008

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	11.9	-	12	12.1	mm
E	package width	11.9	-	12	12.1	mm
A	seated height	0.95	-	1.05	1.2	mm
A ₂	package height	0.65	-	0.7	0.8	mm
n ₂	actual quantity of termination	-	-	144	-	



2. Package outline

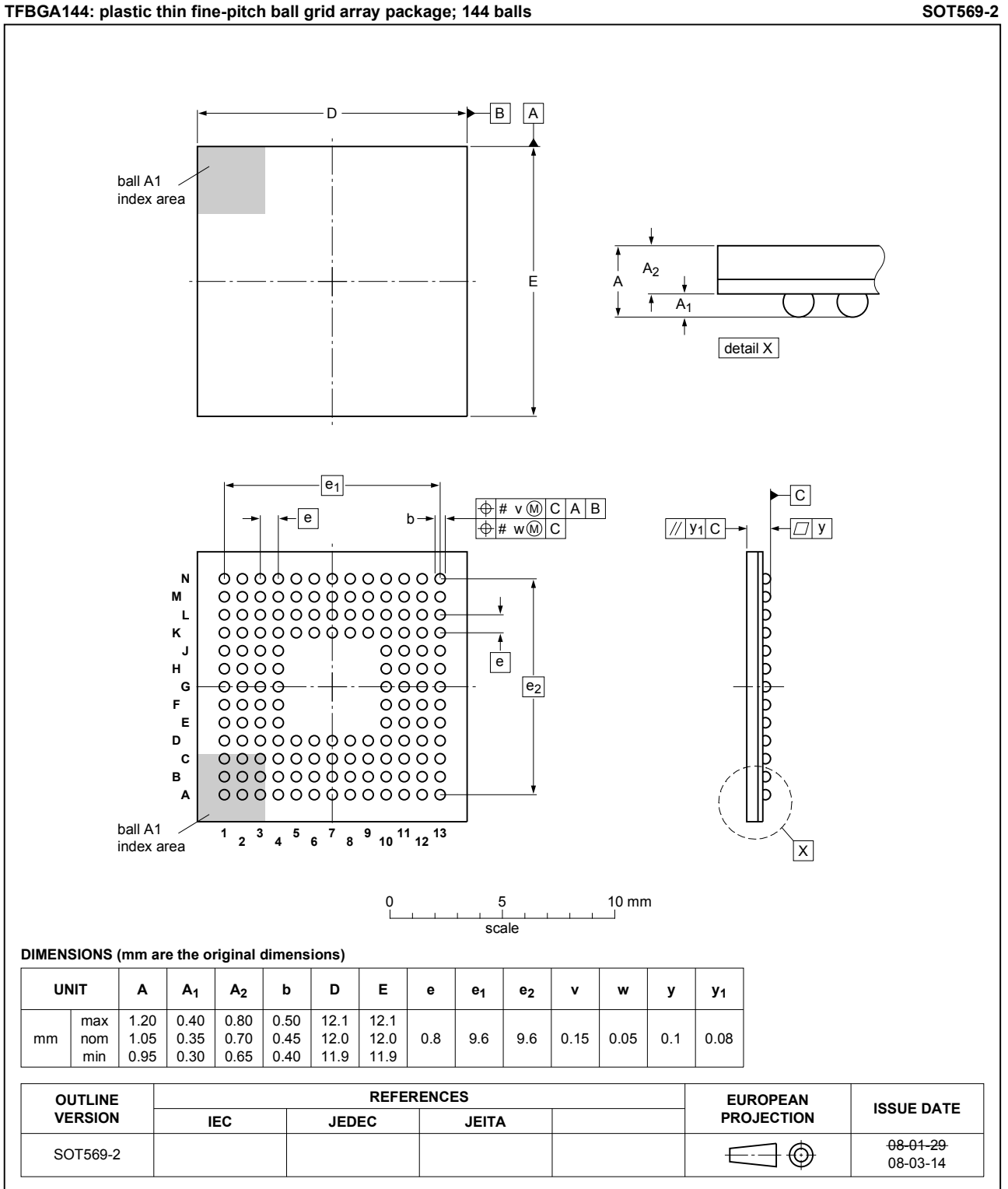


Fig. 1. Package outline TFBGA144 (SOT569-2)

3. Soldering

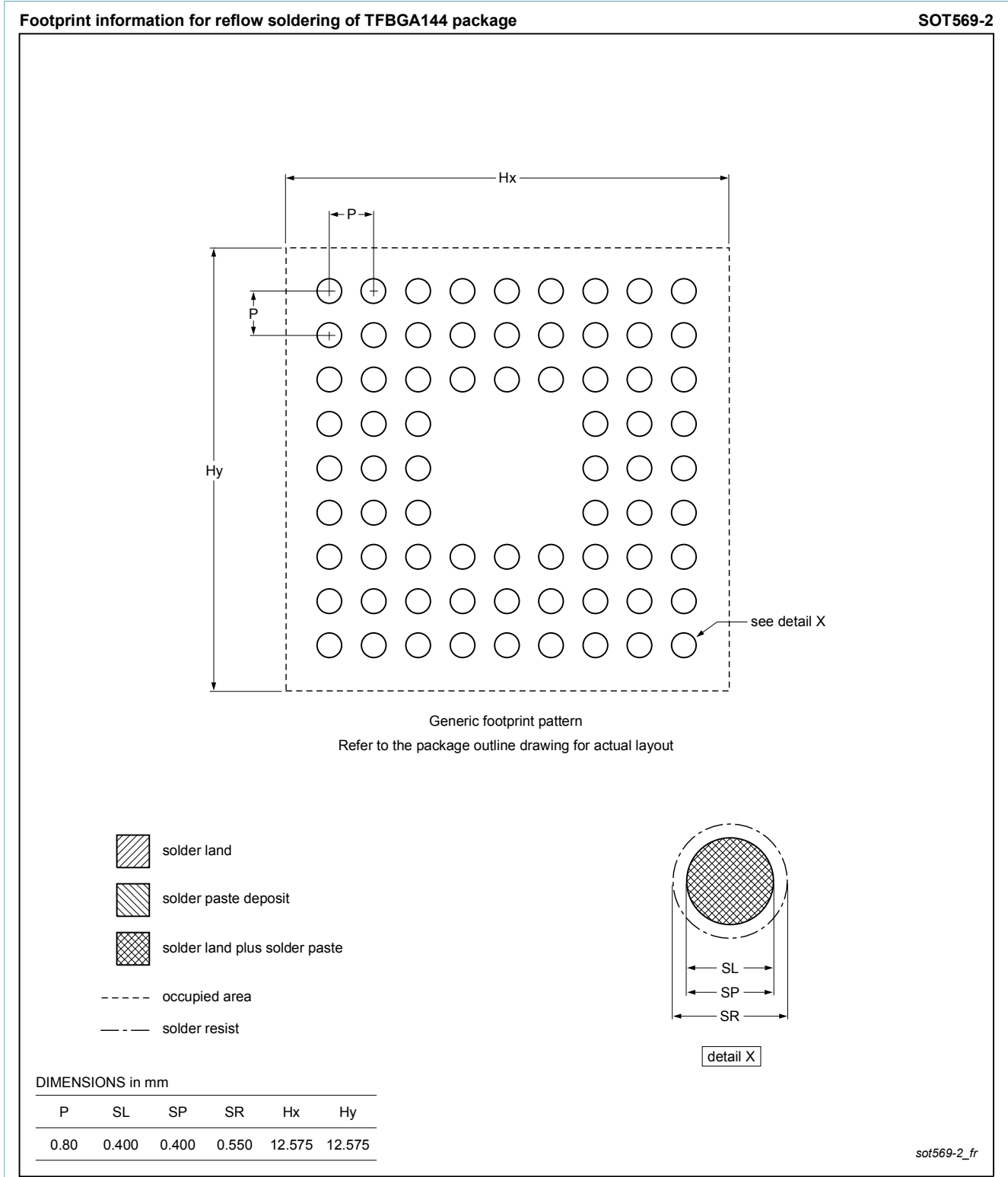


Fig. 2. Reflow soldering footprint for TFBGA144 (SOT569-2)

4. Legal information

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